

Full Material Declaration for PZU9.1B3A

Date	2025-03-21 15:00:10 CET+0100
Package	SOD323 (SOD2): 1.1 mm × 1.25 mm × 1.7 mm
Description	Single Zener diodes
Datasheet	https://assets.nexperia.com/documents/data-sheet/PZUXBA_SER.pdf
OPNs	934062805115: PZU9.1B3A,115 (DOD), MSL 1
Automotive-qualified	No
UL-94	https://iq.ulprospector.com/en/profile?e=574821



REACH	Compliant with Regulation 1907/2006/EC (REACH). Does not contain REACH SVHC substances exceeding 1000 ppm of the article.
EU RoHS	Compliant with Directive 2011/65/EU, amended by Directive 2015/863/EU, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ('RoHS 2 amended') without exemptions.
CN RoHS	Compliant with Chinese Administration on the Control of Pollution Caused by Electronic Information Products (ACPEIP; CN RoHS).
ELV	Compliant with Directive 2000/53/EC, amended by Directive 2023/533, on end of life vehicles (ELV) without exemptions.
PFAS	Does not contain any intentionally added per- and polyfluoroalkyl substances (PFAS).
CA Proposition 65	Contains California Proposition 65 substance(s) [at the article level]: substance 7439-92-1: 94 ppm; substance 1333-86-4: 1939 ppm;
IEC 62474	Contains IEC 62474 substance(s) [at the article level]: substance 7439-92-1: 94 ppm; substance 1333-86-4: 1939 ppm;
Precious Metals	Contains precious metals [Ag, Au, Pd, Pt; at the article level]: substance 7440-22-4: 6264 ppm;
GADSL	Contains 'Global Automotive Declarable Substances List' (GADSL) substances: substance 7440-50-8: 294047 ppm; substance 7439-92-1: 94 ppm; substance 7440-22-4: 6264 ppm;
RHF Indicator	D: Lead-free and halogen-free according to Nexperia's halogen-free definition.

Material	Mat. Group	Substance	CAS No.	Mass / mg	Mass-% of Material	Mass-% of Part
Die	Doped silicon	Silicon (Si)	7440-21-3	0.050000	100.000000	1.205428
Die Total				0.050000	100.000000	1.205428
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	1.216512	95.040000	29.328355
Lead Frame	Copper alloy	Iron (Fe)	7439-89-6	0.032640	2.550000	0.786903
Lead Frame	Copper alloy	Zinc (Zn)	7440-66-6	0.002560	0.200000	0.061718
Lead Frame	Copper alloy	Phosphorus (P)	7723-14-0	0.001920	0.150000	0.046288
Lead Frame	Copper alloy	Lead (Pb)	7439-92-1	0.000384	0.030000	0.009258
<i>Base Alloy Total</i>				<i>1.254016</i>	<i>97.970000</i>	<i>30.232522</i>
Lead Frame	Pure metal layer	Silver (Ag)	7440-22-4	0.025984	2.030000	0.626437
<i>Pre-Plating Total</i>				<i>0.025984</i>	<i>2.030000</i>	<i>0.626437</i>
Lead Frame Total				1.280000	100.000000	30.858959
Mould Compound	Filler	Silica fused	60676-86-0	2.013734	75.100000	48.548231
Mould Compound	Polymer	o-Cresol-epichlorohydrin-formaldehyde copolymer	29690-82-2	0.469246	17.500000	11.312846
Mould Compound	Polymer	Formaldehyde-phenol copolymer	9003-35-4	0.190380	7.100000	4.589788
Mould Compound	Pigment	Carbon black	1333-86-4	0.008044	0.300000	0.193929
Mould Compound Total				2.681404	100.000000	64.644794
Post-Plating	Tin solder	Tin (Sn)	7440-31-5	0.133254	99.940000	3.212562
Post-Plating	Impurity	Non-declarable		0.000074	0.055500	0.001784
Post-Plating	Impurity	Lead (Pb)	7439-92-1	0.000006	0.004500	0.000145
Post-Plating Total				0.133334	100.000000	3.214491

Material	Mat. Group	Substance	CAS No.	Mass / mg	Mass-% of Material	Mass-% of Part
Wire	Pure metal	Copper (Cu)	7440-50-8	0.003166	100.000000	0.076328
Wire Total				0.003166	100.000000	0.076328
PZU9.1B3A Total				4.147904	100.000000	100.000000

部件名称 Material	有毒或有害物质和元素 (Toxic or hazardous substances and elements)					
	铅 (Pb)	镉 (Cd)	汞 (Hg)	六价铬 (Cr ⁶⁺)	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
半导体芯片 (Die)	○	○	○	○	○	○
基底合金 (Base Alloy)	○	○	○	○	○	○
预镀层 (Pre-Plating)	○	○	○	○	○	○
模封料 (Mould Compound)	○	○	○	○	○	○
后镀层 (Post-Plating)	○	○	○	○	○	○
导线 (Wire)	○	○	○	○	○	○

- 表示该有害物质在该部件所有均质材料中的含量均在 GB/T 26572 规定的限量要求以下
- Indicates that said hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement of GB/T 26572.

- 表示该有害物质至少在该部件的某一均质材料中的含量超出 GB/T 26572 规定的限量要求
- × Indicates that said hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement of GB/T 26572.

该半导体产品具有无限期的环保使用期限 (EFUP) 。

This semiconductor product has an indefinite environmental friendly use period (EFUP).

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.